

This document describes the storage conditions and shelf life recommended by Murata Integrated Passive Solutions for their Silicon Capacitors and IPD (Integrated Passive Device). This document is non-exhaustive. Customers with specific requirements that are not covered by this document should contact Murata (mis@murata.com).

Table of contents

1. Storage precautions.....	2
2. Products storage and shelf life	2
2.1 Unsawn wafers.....	3
2.2 Sawn wafers	3
2.3 Packing options.....	4
Revision history	6
Disclaimer / Life support applications	6



1. Storage precautions

Store the capacitors in the manufacturer's package as much as possible, without any rapid thermal change. As much as possible, usage of complete packing units (waffle pack, FFC, tape and reel...) is recommended and remaining quantities have to be repacked immediately after any process step.

Avoid storing the capacitors in the following conditions:

- (a) Ambient air containing corrosive gas (Chlorine, Hydrogen sulfide, Ammonia, Sulfuric acid, Nitric oxide, etc.)
- (b) Ambient air containing volatile or combustible gas
- (c) In environments with a high concentration of airborne particles
- (d) In liquid (water, oil, chemical solution, organic solvents, etc.)
- (e) Under direct sunlight
- (f) In freezing environment

To avoid contaminations and damages, even during storage and packing handling:

- Dies or wafers must never be handled with bare hands
- Avoid touching or scratching the active face with tools that are not adapted
- The mechanical pressure has to be limited
- Do not store and transport dies outside protective bags, tapes or boxes
- Work only in ESD safe environments

2. Products storage and shelf life

Shelf life depends on packing and on UV exposure as detailed in following tables.

Please note production date on labeling.



2.1 Unsawn wafers

Packing	Murata recommendations
Original shipping carrier	6 years 8°C to 45°C & RH<30% (or dried N2)
Round container <i>Figure 1</i>	6 years 8°C to 45°C & RH<30% (or dried N2) Wafers must be separated by foam
After unpacking	Must be used ASAP then follow below recommendations
Conductive bags <i>Figure 4</i>	5 years

Figure 1: Storage recommendations for unsawn wafers.

2.2 Sawn wafers

Packing	Murata recommendations
Film frame carrier D175 Adwill (obsolete) <i>Figures 1 and 2</i>	UV performed 12 Months 18-40°C & RH<60% (or dried N2) in the dark
	UV not performed 12 Months 23 +/- 5°C & RH<80% (or dried N2) in the dark
Film frame carrier D-686H Adwill <i>Figures 1 and 2</i>	UV performed 12 Months 18-40°C & RH<60% (or dried N2) in the dark
	UV not performed 12 Months 23 +/- 5°C & RH<80% (or dried N2) in the dark
Expander grip ring D-686H <i>Figure 2</i>	UV performed 12 Months 18-40°C / RH<60% (or dried N2) in the dark
	UV not performed (1) After irradiation 12 Months 18-40°C & RH<60% (or dried N2) in the dark
Film frame carrier or Ring expander D510 Adwill <i>Figures 1 and 2</i>	UV performed 12 Months 18-40°C & RH<60% (or dried N2) in the dark
	UV not performed 12 Months 23 +/- 5°C & RH<80% (or dried N2) in the dark
Tape and reel <i>Figure 3</i>	5 years (2) 18-35°C & 35%<RH<65% (or dried N2)
Gel pack <i>Figure 3</i>	5 years (2) 18-35°C & 35%<RH<65% (or dried N2)
Waffle pack <i>Figure 3</i>	2 years (2) 18-35°C & 35%<RH<65% (or dried N2)
Conductive bags <i>Figure 4</i>	5 years

Figure 2: Storage recommendations for sawn wafers and products from sawn wafers.

(1) UV irradiation needs to be done as soon as possible upon wafer reception.

Here are some recommendations about the specific UV irradiation parameters and the equipment used for D-686H foil.



Equipment - RAD2000F / 8 (Lintec equipment - 200mm fully-automatic UV irradiation system)

UV irradiation conditions are:

- o UV ray intensity = 260mW / cm² (adjustable via a potentiometer)
- o UV ray dosage = 220mJ / cm² (determined by scanning speed)

(2) Tape and reel, Gel pack and Waffle pack must be stored as much as possible in their original protective bags.

2.3 Packing options

Some examples of packing:



Figure 1: From left to right, a single metal frame used for Film Frame Carrier; two frames and a malaster box; an opened malaster box with wafers on Film Frame Carrier within; a round container for wafers.

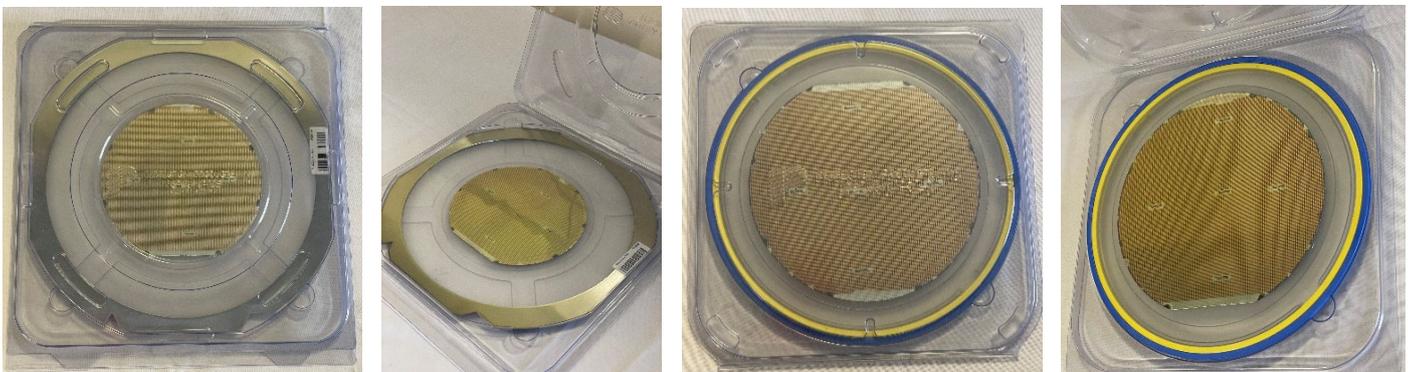


Figure 2: From left to right, a wafer on FFC within a plastic transportation box; the same box opened; a wafer on expander grip ring (yellow and blue) within its plastic transportation box; the same box opened.



Figure 3: From left to right, tape and reel on top plus cut tape on bottom; a gel pack with transparent cover; a waffle pack with pockets inside, its black cover, a clip and a completed waffle pack.



Figure 4: From left to right, a waffle pack inside a sealed conductive bag; a conductive bag for tape and reel inside its cardboard transportation box; the same box for side view.



Revision history

Revision	Date	Description	Author
1.5	21/05/2021	Updated version and format	C Muller
1.6	19/01/2023	Update on storage and assembly conditions	K.Dubois

Disclaimer / Life support applications

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